Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP OMEN X by HP 15 Laptop

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [x] screws [ ] snaps [ ] adhesive [ ] other. Explain ______. NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps 15.6”</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Item Description</td>
<td>Notes</td>
<td>Quantity of items included in product</td>
</tr>
<tr>
<td>---------------------------------------------------------------------------------</td>
<td>----------------------------------------------------------------------</td>
<td>---------------------------------------</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw Driver</td>
<td>#1</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Dis-fasten BASE Screw*6
2. Remove BASE and remove Battery connector
3. Dis-fasten SSD screw*2
4. Remove SSD*2 PCS and Ram*2PCS
5. Dis-fasten Battery and speaker screw*7
6. Remove Battery and Speaker
7. Dis-fasten IO BKT and DC BKT screw*4
8. Remove IO BKT and DC BKT
9. Dis-fasten Thermal model Screw*6 and Relase Thermal modle screw*7
10. Remove Thermal module and DC in Cable
11. Dis-fasten PCB screw *7 and 2nd panel DB screw*2
12. Release KB FPC/ 2nd panel DB /Antenna connector /IR FFC / LVDS FPC /Power FFC and Remove MB PCB
13. Dis-fasten Cu plate screw *1/ Power screw*1 and IR DB screw*2
14. Remove Cu Plate and KB FPC
15. Remove 2nd DB with 2nd Panel FPC / IR DB with IR FFC and Power DB
16. TOP remove release, dis-fasten Hinge screw *6 and remove LCD part
17. Remove Bezel , dis-fasten hinge cap screw*2 and remove hing cap*2PCS
18. Dis-fasten Hinge screw*6
19. Remove Panel Easy pull Adhesive
20. Remove Panel and Hinge*2PCS

HPI instructions for this template are available at [EL-MF877-01](EL-MF877-01)
21. Dis-fasten hinge bkt screw *6
22. Remove LVDS FPC/ Backlight module / Hinge BKT*2PCS /Camera module
23. Remove Antenna module and Backlight DB
24. END

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Dis-fasten BASE Screw*6

3.22 Remove BASE and remove Battery connector

3.23 Dis-fasten SSD screw*2

HPI instructions for this template are available at EL-MF877-01
3.24 Remove SSD*2 PCS and Ram*2PCS

3.25 Dis-fasten Battery and speaker screw*7

3.26 Remove Battery and Speaker
3.27 Dis-fasten IO BKT and DC BKT screw*4

3.28 Remove IO BKT and DC BKT

3.29 Dis-fasten Thermal model Screw*6 and Relase Thermal model screw*7
3.30 Remove Thermal module and DC in Cable

3.31 Dis-fasten PCB screw *7 and 2\textsuperscript{nd} panel DB screw*2

3.32 Release KB FPC/ 2\textsuperscript{nd} panel DB /Antenna connector /IR FFC / LVDS FPC /Power FFC and Remove MB PCB
3.33 Dis-fasten Cu plate screw *1/ Power screw*1 and IR DB screw*2

3.34 Remove Cu Plate and KB FPC

3.35 Remove 2nd DB with 2nd Panel FPC / IR DB with IR FFC and Power DB
3.36 TOP remove release, dis-fasten Hinge screw *6 and remove LCD part

3.37 Remove Bezel, dis-fasten hinge cap screw*2 and remove hinge cap*2PCS

3.38 Dis-fasten Hinge screw*6
3.39 Remove Panel Easy pull Adhesive

3.40 Remove Panel and Hinge*2PCS

3.41 Dis-fasten hinge bkt screw *6
3.42 Remove LVDS FPC/ Backlight module / Hinge BKT*2PCS /Camera module

3.43 Remove Antenna module and Backlight DB

3.44 END